

Digital Signal Processor for Karaoke Products

Overview

The LC83025E is a special-purpose karaoke DSP that implements the signal processing required by karaoke systems, including pitch shift, microphone echo, voice muting and simple surround, with only a single 256Kb external DRAM. Since the LC83025E includes built-in A/D and D/A converters, it can also handle analog inputs and outputs in addition to digital inputs and outputs. The LC83025E uses serial transfer of coefficient data from a microcontroller to handle changes in functions and characteristics required for each application.

Features

- · Applications
 - Pitch shift

The LC83025E can shift the music pitch or the microphone pitch by ± 15 steps in 1/4 interval steps, or ± 1 octave in scale tone steps according to command data sent from the microcontroller. Furthermore, the pitch can be changed up to ± 1 octave in arbitrary steps by setting internal coefficients.

- Microphone echo

The LC83025E implements echo processing for the signal input from the microphone A/D converter. The amount of echo, the delay time and other parameters can be changed by setting coefficients.

— Voice mute

The LC83025E implements processing that removes monaural signal components included in the music signal. This allows CDs with vocals to be used as karaoke CDs. Command data is used to turn the voice mute function on or off.

Simple surround

The LC83025E implements a simple surround function by adding delayed components to the music signal. The LC83025E includes six sets of simple surround coefficients as built-in preset data. These values can be switched by sending command data. Applications can implement their own original surround effects by setting the coefficients. However, the algorithm itself is fixed.

- Flexible input mixing
 - The LC83025E supports hybrid mixing of digital and analog left and right channel song inputs, and thus can handle a wide range of disk processing configurations.
- · Audio inputs and outputs
 - Inputs: Digital One system (stereo)

A/D converter - Three channels

Outputs Digital - One system (stereo)

D/A converter / Two channels

A/D converter

Second order $\Delta \Sigma$ modulation - Three channels

D/A converter

4× oversampling digital filters plus second order noise shaper

plus 5-bit PWM system - Two channels

Master clock: 768 fs

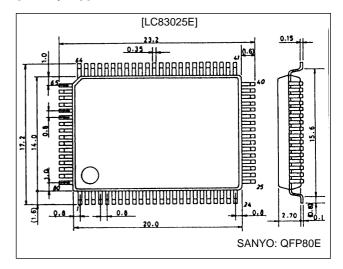
- External memory: Up to two 256K (64K × 4-bit)

 DRAMs can be used
- Microcontroller input: Synchronous 8-bit serial data
- Supply voltage: 5 V single-voltage
- Package: QFP80E

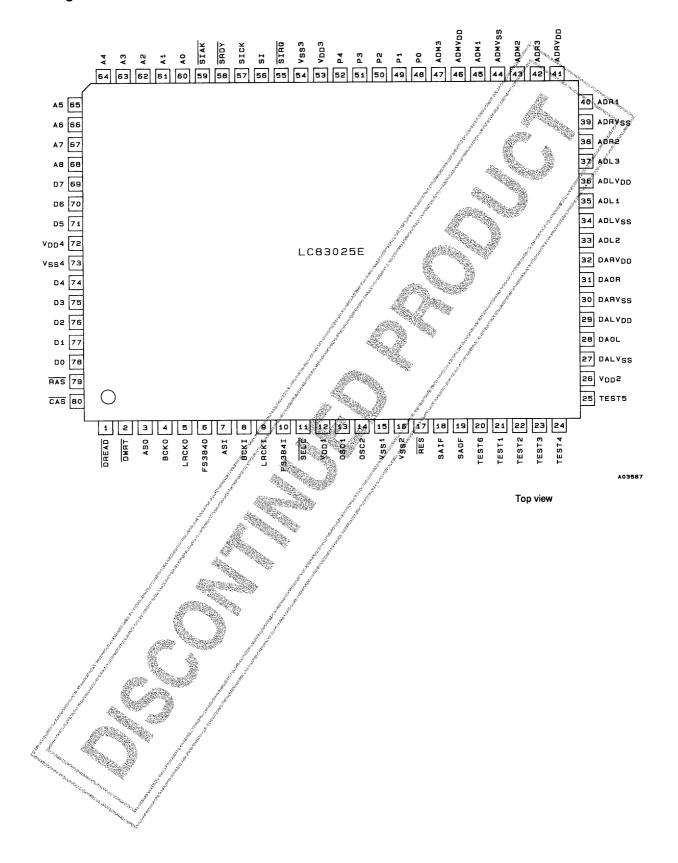
Package Dimensions

unit: mm

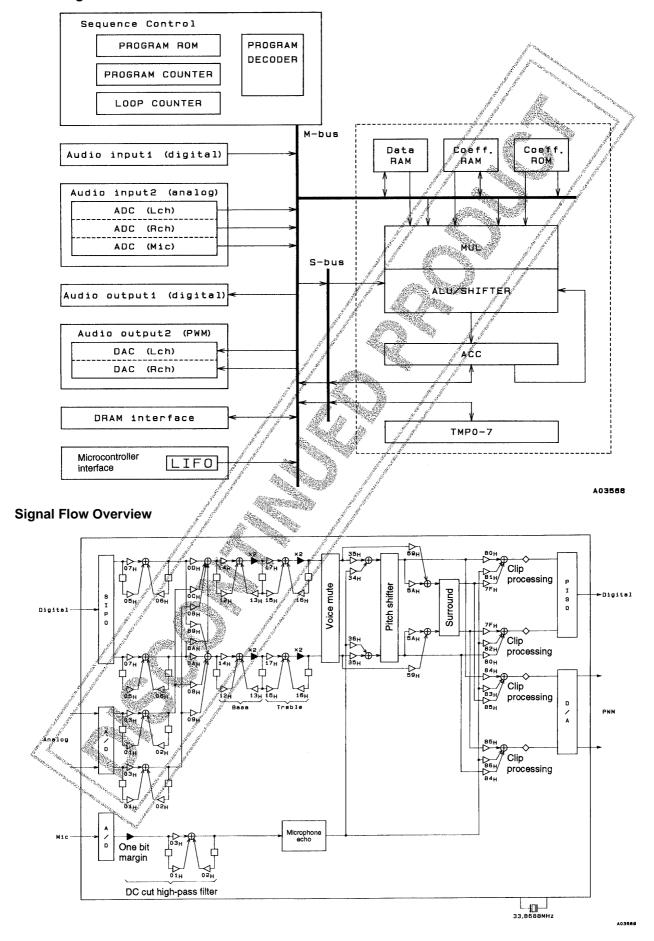
3174-QFP80E



Pin Assignment



Block Diagram



Pin Functions

Pin No.	Symbol	I/O	Function
[Control p	ins]	l	
13	OSC1	I	Crystal oscillator connection (768 fs)
14	OSC2	0	Crystal oscillator connection (768 fs)
10	FS384I	ı	384 fs input (Apply a clock that is equal to the OSC1/OSC2 768 fs clock divided by 2.)
11	SELC	ı	Audio clock source switching (High: Fixes FS384I as the clock)
18	SAIF	ı	Digital audio input mode switching (Low: backward packed, High: forward packed)
19	SAOF	ı	Digital audio output mode switching (Low: 48 fs, High: 64 fs)
17	RES	ı	Reset
25 to 21	TEST5 to TEST1	ı	Test (Must be tied to ground in normal operation.)
20	TEST6	0	Test (Must be left open in normal operation.)
48	P0	ı	Coefficient transfer mode switching
50, 49	P2, P1	ı	Initial operating mode setting (This pin should be held high in normal operation.)
51	P3	0	Microphone signal present (low output) or absent (high output) indication output
52	P4	0	Music signal present (low output) or absent (high output) indication output
[External	memory interface]		
79	RAS	0	RAS signal output
80	CAS	0	CAS signal output
1	DREAD	0	External memory read signal output
2	DWRT	0	External memory write signal output
68 to 60	A8 to A0	0	Address outputs
69 to 71,	B= . Bo	.,,	B . 40 M . 4 . 5 / 20
74 to 78	D7 to D0	I/O	Data I/O (Normally, only D3 to D0 are used)
[Audio int	erface]		
9	LRCKI	I	ASI L/R clock input (1.15)
5	LRCKO	0	ASO L/R clock output (1 fs)
8	BCKI	I	ASI bit clock input (32 fs or higher)
4	ВСКО	0	ASO bit clock output (48 1s or 64 1s)
6	FS384O	0	ASO 384 is output
7	ASI	I	Digital audio data input (MSB first, 16 bits)
3	ASO	0	Digital audio data output (MSB first, backward packed, 16 bits)
35	ADL1	I	A/D converter input (left channel)
33	ADL2	0 /	ØD converter output (left channel)
37	ADL3	Ø/	A/D converter output (left channel)
40	ADR1	F pt	A/D convertee input (right channel)
38	ADR2	ar ^{ze} O	A/D converter output (right channel)
42	ADR3	0	AD converter output (right channel)
45	ADM1	1 💯	A/D converter input (microphone)
43	ADM2	O.	AD converter output (microphone)
47	ADM3	0	D converter output (microphone)
28	√ DAOL	O	DA converter output (left channel)
31	/DAOR	O	D/A converter output (right channel)
[Microcon	troller interface]		
55 📌	Street Notes Street	(S)	Senat input request signal input
59/	SIAK	0	Output indicating serial input execution in progress
-56 ⁻⁽ -)	SI	I 🎉	Serial data input from the control microcontroller (8-bit serial data)
57	SIČK	11	SI transfer clock input
58	SRDY	11	Ready signal input from the control microcontroller that indicates that serial data input has completed
	The same of	, profession .	

Continued from preceding page.

Pin No.	Pin No. Symbol I/O Function									
[Power su	[Power supply pins]									
12, 26, 53, 72	7 7 1 V 1 DD 0 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \									
15, 16, 54, 73	15, 16, V _{SS} for the digital block (Connect to ground.)									
36	ADLV _{DD}	-	A/D converter V _{DD} (left channel) (Connect to +5 V.)	Design the orblination will be as						
41	ADRV _{DD}	-	A/D converter V _{DD} (right channel) (Connect to +5 V.)	Design the application witing so that potential differences do not						
46	ADMV _{DD}	-	A/D converter V _{DD} (microphone) (Connect to +5 V.)	occur between the analog V _{DD}						
29	DALV _{DD}	-	D/A converter V _{DD} (left channel) (Connect to +5 V.)	pins and between the digital V _{DD}						
32	DARV _{DD}	-	D/A converter V _{DD} (right channel) (Connect to +5 V.)	- gloup and the analog vDD group.						
34	ADLV _{SS}	-	A/D converter V _{SS} (left channel) (Connect to ground.)	Design the application wiring so						
39	ADRV _{SS}	-	A/D converter V _{SS} (right channel) (Connect to ground.)	that potential differences do not						
44	ADMV _{SS}	-	A/D converter V _{SS} (microphone) (Connect to ground)	occur between the analog V _{SS}						
27	DALV _{SS}	-	D/A converter V _{SS} (left channel) (Connect to ground.)	pins and between the digital V _{SS} group and the analog V _{SS} group.						
30	DARV _{SS}	_	D/A converter V _{SS} (right channel) (Connect to ground.)	Though and the arrange vSS group.						

Pin Circuits

Specification	Circuit	Pins
TTL output		ASO, LRCKO, BCKO, RAS, CAS, DREAD, DWRT, FS384O, A0 to A8
CMOS intermediate current output	Output data	P3, P4, SIAK, TEST6
Analog output	Output data	DAOL, DAOR, ADL2, ADL3, ADM2, ADM3, ADR2, ADR3
Schmitt input	□ Input data	SI, SICK, SIRQ, SRDY, (OSC1)
Low Schmitt input	A03672	FS384I, BCKI, ASI, LRCKI
Normal input	Input data	TEST1 to TEST5
Input with built-in pull-up resistor	Input data	RES
Input with built-in pull-down resistor	Input data	SELC, SAIF, SAOF
CMOS intermediate current output Low Schmitt input	Input data I/O control Output data A03576	D0 to D7
N-channel open drain intermediate current output Normal input	Test output data Off during normal operation A03577	P0 to P2
Analog input	A03573	ADL1, ADR1, ADM1

Specifications

Absolute Maximum Ratings at Ta = 25°C, V_{SS} = 0 V

Parameter	Symbol	Conditions	Ratings	Unit	Note
Maximum supply voltage	V _{DD} max		./-0,3 to +7.0	V	
Output voltage	V _O 1	OSC2 output	Alfowed up to the oscillator voltage.	A Special	
	V _O 2	Pins other than OSC2	-0.3 to V _{DD} + 0.3	V.	
Input voltage	V _{IN}		−0.3 to V _{DD} + 0.3	ŷ j	
Peak output current	I _{OP} 1	Audio interface, external RAM interface	−2 to +4	/m/A	1
r eak output current	I _{OP} 2	Microcontroller interface, P3, P4	– 2 to +10	mΑ	2
	I _{OA} 1	Audio interface, external RAM interface per pin	% - 2 to +4.	mA	1
	I _{OA} 2	Microcontroller interface, P3, P4: per pin	−2 to +10	mA	2
Average output current	ΣI _{OA} 1	Total for FS384O, LRCKO, BCKO, and ASO	-10 to +10	mA	
Average output current	ΣI _{OA} 2	Total for DWRT, DREAD, RAS, CAS, A3 to A8 and D0 to D7	-30 to +30	mA	
	Σl _{OA} 3	Total for A0 to A2, SIAK, P3 and P4	ુ∕ –∮0 to +10	mA	
Allowable power dissipation	Pd max	Ta = −30 to +70°C	700	mW	
Operating temperature	Topr	A State Control of the Control of th	_30 to +70	°C	
Storage temperature	Tstg		-40 to +125	°C	

Allowable Operating Ranges at Ta = -30 to +70°C, all V_{DD} = 4.75 to 5.25 V, all V_{SS} = 0 V unless otherwise specified

Parameter	Symbol	Conditions	min I	typ	max	Unit	Note
Operating supply voltage	V _{DD}	// *** ** //	4.75	-76	5.25	V	11010
operating cupply remage	V _{IH} 1	Audio interface, external RAM interface	2.4		0.20	V	4
Input high level voltage	V _{IH} 2	P0 to P2, SELC, SAIF, SAOF, TEST1 to TEST5	0.7 V _{DD}			V	5
pg	V _{IH} 3	RES, OSC1, microcontroller interface	0.75 V _{DD}			V	6
	V _{II} 1	Audio interface external RAM interface	1 00		0.8	V	4
Input low level voltage	V _{IL} 2	P0 to P2, SELC, SAIF, SAOF, TEST1 to TEST5			0.3 V _{DD}	V	5
	V _{IL} 3	RES, OSC1, microcontroller interface			0.25 V _{DD}	V	6
Instruction cycle time	tcyç		58		59.11	ns	
[External Clock Input Conditions]			1				
Frequency	^f EXT		16.85		17.01	MHz	
- · · · · ·	† Exth	Related to the FS384I pin. Shown in Figure 1.	23			ns	
Pulse width	t _{EXTL}	max: 44.1 kHz × 384 × 1.005	23			ns	
Rise time	t _{EXTR}	min: 44.1 kHz × 38.4 × 0.995			9	ns	
Fall time	textr.	*			9	ns	
[Self-Excitation Oscillation Condition					'		
Oscillator frequency	fosc	OSC1 and OSC2: shown in Figure 2. 44.1 kHz × 768 × ± 0.1%	33.84		33.90	MHz	
Oscillator stabilization period	foses	Shown in Figure 3.			100	ms	
[Audio Data Input Conditions]	10.6				'		1
Transfer bit clock period	t _{BCYC}	Leave the second	354			ns	
Transfer bit clock pulse width	t _{BCW} /	Poloto data the DOM and AOI nine. Observe in Figure 4	100			ns	
Data setup time	ţs	Related to the BCKI and ASI pins. Shown in Figure 4.	70			ns	
Data hold time	t _l a"		70			ns	
[Serial Input Clock Conditions]	11						
Serial clock period	/ t _{scyc}		480			ns	
Serial clock pulse width	t _{SCW}		200			ns	
Data setup time	t _{SS}	Related to the microcontroller interface. Shown in	70			ns	
Data hold time	t _{SH}	Figure 5. (Related to the SICK, SI and SRDY pins.)	70			ns	
SRDY hold time t _{SYH}			200			ns	
SRDY pulse width t _{SYW}			200			ns	
[DRAM Input Conditions]					•		
Input data setup time	t _{DSI}	Related to external DRAM data input. Shown in Figure 6.	20			ns	
Input data hold time	t _{DHI}	(Related to the CAS and D0 to D7 pins.)	0			ns	

Electrical Characteristics 1

at Ta = –30 to +70°C, all V_{DD} = 4.75 to 5.25 V, all V_{SS} = 0 V unless otherwise specified

Input low level current	Parameter	Symbol	Conditions	min	typ	max	Unit	Note
I _{II.3} Other input-only pins		I _{IL} 1	RES, V _{IN} = V _{SS} (Input pins with built-in pull-up resistor)	-250	- 100	D. Actor	μA	8
Input high level current	Input low level current	I _{IL} 2	P0 to P2, V _{IN} = V _{SS}	-10		No. of the second	μΑ	
Input high level current Input high level voltage VoH1 IoH = −0.4 mA		I _{IL} 3	Other input-only pins	-10	1 .	W. A. L. Carrier	μA	
H ₁ H ₂ Prot b P ₂ , V _{IN} = V _{DD} (n-channel transistor off) H ₂ Prot b P ₂ , V _{IN} = V _{DD} (n-channel transistor off) H ₂ Prot b P ₂ , V _{IN} = V _{DD} (n-channel transistor off) H ₂ Prot b P ₂ , V _{IN} = V _{DD} (n-channel transistor off) V _D V		I _{IH} 1	SELC, SAIF, SAOF, V _{IN} = V _{DD} (Input pins with built-in pull-down resistor)	September 1	100	250	μA	8
Output high level voltage VoH1 VoH2 VoH2 VoH3 VoH3 VoH3 VoH3 V VoH3 VoH3 VoH3 V VoH3 VoH3 VoH3 V VoH3 VoH3 VoH3 V VoH3 VoH3 VoH3 VoH3 V VoH3 VoH3 VoH3 VoH3 VoH3 VoH3 VoH3 VoH	Input high level current	I _{IH} 2	P0 to P2, V _{IN} = V _{DD} (n-channel transistor: off)	1. F. J.		10	μÁ	
Vop		I _{IH} 3	Other input-only pins	g steril		. 10	μÁ	
Vop	Output high lavel valtage	V _{OH} 1	I _{OH} = -0.4 mA	4.0	4,98		* V	1, 8
Output low level voltage V _{OL} 1 I _{OL} = 2 mA 0.365 0.4 V 1, 8 Output off leakage current I _{OFF} V _O = V _{SS} . V _{DD} 46 √4.40 µA I/O capacitance C _{IO} 10 pF V _O = V _{SS} . V _{DD} 46 √4.40 µA I/O capacitance C _{IO} 10 pF V _O = V _{SS} . V _{DD} 46 √4.40 µA I/O capacitance C _{IO} 10 pF V _O = V _{SS} . V _{DD} 46 √4.40 µA I/O capacitance C _{IO} 10 pF V _O = V _{SS} . V _{DD} 46 √4.40 µA I/O capacitance C _{IO} 10 pF V _O = V _{SS} . V _{DD} 40 n ns 7 00 ns 7 <td< td=""><td>Output high level voltage</td><td></td><td></td><td>V_{DD} – 1.2</td><td>4.997</td><td>and the second</td><td>V</td><td>2, 3, 8</td></td<>	Output high level voltage			V _{DD} – 1.2	4.997	and the second	V	2, 3, 8
Vol.2 I _{OFF} Vo = V _{SS} , V _{DD} 40	Output law lavel valtage	V _{OL} 1	I _{OL} = 2 mA	1600	0.065	0.4	V	1, 8
Variable	Output low level voltage	V _{OL} 2	I _{OL} = 10 mA	W/4, 40	0.32	1 .5	V	2, 3, 8
Audio Data Output Timing	Output off leakage current	I _{OFF}	$V_O = V_{SS}, V_{DD}$	-4 0	gad	/ +40	μA	
Output data hold time t _{OH} BCKO and ASO: shown in Figure 7 -30 / 50 / ns 7 Output data delay time t _{OD} 50 / ns 7 (External DRAM Access Timing) RAS high pulse width t _{RP} 80 / ns 7 RAS low pulse width t _{RAS} 700 / ns 7 CAS high pulse width t _{CP} 50 / ns 7 CAS low pulse width t _{CAS} 95 / ns 7 CAS low pulse width t _{CAS} 95 / ns 7 CAS low pulse width t _{CAS} 95 / ns 7 CAS low pulse width t _{CAS} 95 / ns 7 RAS to CAS delay time t _{RCD} 175 / ns 7 RAS hold time t _{CSH} 170 / ns 7 RAS address setup time t _{ASR} 170 / ns 7 CAS address setup time t _{ASR} 30 / ns 7 CAS address setup time t _{ASR} 30 / ns 7 Write command setup time t _{VCS} 90 / ns 7 Write command hold time t	I/O capacitance	C _{IO}		\$10A	je se	10	pF	
Dutput data delay time	[Audio Data Output Timing]				part de			
Output data delay time top 50 ns 7 External DRAM Access Timing] RAS high pulse width t _{RAS} 80 ns 7 RAS low pulse width t _{RAS} 700 ns 7 CAS high pulse width t _{CAS} 50 ns 7 CAS low pulse width t _{CAS} 95 ns 7 CAS cycle time t _{PC} 175 ns 7 RAS to CAS delay time t _{RCD} 60 ns 7 RAS hold time t _{RSH} 170 ns 7 RAS address setup time t _{ASR} 170 ns 7 Shown in Figure 8. 95 ns 7 Shown in Figure 8. 20 ns 7 CAS address setup time t _{ASR} 30 ns 7 DWRT pulse width t _{WP} 95 ns 7 Write command setup time t _{WC} 90 ns 7 Write command brold time t _W 12	Output data hold time	t _{OH}	BCKO and ASO: shown in Figure 7	-30	Jan San San San San San San San San San S		ns	7
RAS high pulse width t _{RP} RAS low pulse width t _{RAS} CAS high pulse width t _{CP} CAS high pulse width t _{CP} CAS low pulse width t _{CAS} CAS cycle time t _{PC} RAS to CAS delay time t _{RCD} CAS hold time t _{CSH} RAS hold time t _{RSH} RAS address setup time t _{ASR} RAS address hold time t _{RAH} CAS address hold time t _{ASC} CAS address hold time t _{CAH} DWRT pulse width t _{WC} Write command setup time t _{WC} Write command hold time t _{WC} Output data setup time t _{DSO} Output data hold time t _{DHO} Crystal oscillator C2 C2 DSC1 and OSC2 shown in Figure 2. 29 L L L L	Output data delay time	t _{OD}	BONO and ASO. Shown in Figure 7.		St. St.	50	ns	7
RAS low pulse width t _{RAS}	[External DRAM Access Timing]			10	ş*			
CAS high pulse width t _{CP} CAS low pulse width t _{CAS} CAS cycle time t _{PC} RAS to CAS delay time t _{RCD} CAS hold time t _{CSH} RAS address setup time t _{ASR} RAS address setup time t _{ASR} RAS address setup time t _{ASR} CAS address setup time t _{ASC} CAS address hold time t _{CAH} DWRT pulse width t _{WP} Write command setup time t _{WCS} Write command hold time t _{WCH} Output data setup time t _{DSO} Output data hold time t _{DHO} Crystal oscillator t _{DHO} Casc and adversarial DRAM 50 ns 7 day ns t _C ns	RAS high pulse width	t _{RP}	1/ /200	/ /80			ns	7
CAS low pulse width t _{CAS} CAS cycle time t _{PC} RAS to CAS delay time t _{RCD} CAS hold time t _{CSH} RAS hold time t _{RSH} RAS address setup time t _{ASR} RAS address hold time t _{RAH} CAS address setup time t _{ASC} CAS address hold time t _{ASC} CAS address hold time t _{CAH} DWRT pulse width t _{WP} Write command setup time t _{VCS} Write command hold time t _{WCH} Output data setup time t _{DSO} Output data hold time t _{DHG} Corystal oscillator C1 OSC1 and OSC2: shown in Figure 2. 13 C2 29 DF 8 Command the time t _{DHG} C1 OSC1 and OSC2: shown in Figure 2. C2 29 DF 8 C2 29 DF 8	RAS low pulse width	t _{RAS}		<i>f</i> 700			ns	7
CAS cycle time tpC RAS to CAS delay time t_RCD CAS hold time t_CSH RAS hold time t_RSH RAS address setup time t_ASR RAS address setup time t_ASR Timing for output fo the external DRAM. 60 Shown in Figure 8. 95 Timing for output fo the external DRAM. 60 Shown in Figure 8. 20 To Saddress setup time t_ASC CAS address hold time t_CAH DWRT pulse width t_WP Write command setup time t_WCH Write command hold time t_WCH Output data setup time t_DSO Output data hold time t_DHO Crystal oscillator C1 CSC1 and OSC2: shown in Figure 2. 13 DF 8 CC2	CAS high pulse width	t _{CP}		<i>,</i> 50			ns	7
RAS to CAS delay time t_RCD	CAS low pulse width	t _{CAS}		95			ns	7
CAS hold time t _{CSH} RAS hold time t _{RSH} RAS address setup time t _{ASR} RAS address hold time t _{RAH} CAS address setup time t _{ASC} CAS address hold time t _{ASC} CAS address hold time t _{CAH} DWRT pulse width t _{WP} Write command setup time t _{WCS} Write command hold time t _{WCH} Output data setup time t _{DSO} Output data hold time t _{DHG} Crystal oscillator C1 Casc1 and OSC2: shown in Figure 2. 113 Description pF 8 20 ns 7 90 ns ns 7 Write command hold time t _{WCH} 0utput data setup time t _{DSO} 0utput data hold time t _{DSO} 100 ns 7 22 29 23 pF 8 24 1.5 11 1.	CAS cycle time	t _{PC}		175			ns	7
RAS hold time	RAS to CAS delay time	t _{RCD}		60			ns	7
Timing for output to the external DRAM Shown in Figure 8. Shown in Figure 8. CAS address setup time t_ASC CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time t_CAH Shown in Figure 8. CAS address hold time Shown in Figure 9. CAS address hold time	CAS hold time	t _{CSH}		170			ns	7
RAS address sclup time t_RAH	RAS hold time	t _{RSH}		95			ns	7
RAS address hold time	RAS address setup time	t _{ASR}		60			ns	7
CAS address setup time t _{ASC} CAS address hold time t _{CAH} DWRT pulse width 90 Write command setup time t _{WP} Write command hold time t _{WCH} Output data setup time t _{DSO} Output data hold time t _{DHO} Crystal oscillator 12 C1 OSC1 and OSC2: shown in Figure 2. C2 13 DF 8 C1 0SC1 and OSC2: shown in Figure 2. L 1.5 L 1.5	RAS address hold time		Shewn in rigure 8.	20			ns	7
CAS address hold time t _{CAH} 90 ns 7 DWRT pulse width t _{WP} 95 ns 7 Write command setup time t _{WCS} 12 ns 7 Write command hold time t _{WCH} 65 ns 7 Output data setup time t _{DSO} 30 ns 7 Output data hold time t _{DHO} 100 ns 7 Crystal oscillator C1 OSC1 and OSC2: shown in Figure 2. 29 pF 8 Command the properties of the proper	CAS address setup time			30			ns	7
DWRT pulse width t _{WP} Write command setup time t _{WCS} Write command hold time t _{WCH} Output data setup time t _{DSO} Output data hold time t _{DHO} Country 100 To SC1 and OSC2: shown in Figure 2. 13 C2 29 DWRT pulse width 12 12 ns 7 30 100 ns 13 pF 8 C2 29 PF 8 Convent design 1.5	CAS address hold time			90			ns	7
Write command hold time t _{WCH} 65 ns 7 Output data setup time t _{DSO} 30 ns 7 Output data hold time t _{DHO} 100 ns 7 Crystal oscillator C1 0SC1 and 0SC2: shown in Figure 2. 13 pF 8 C2 PF 8 C2 L 1.5 μH 8	DWRT pulse width	.500 .400		95			ns	7
Write command hold time t _{WCH} 65 ns 7 Output data setup time t _{DSO} 30 ns 7 Output data hold time t _{DHO} 100 ns 7 Crystal oscillator C1 0SC1 and 0SC2: shown in Figure 2. 13 pF 8 C2 PF 8 C2 L 1.5 μH 8	Write command setup time	twcs		12			ns	7
Output data setup time t _{DSO} 30 ns 7 Output data hold time t _{DHO} 100 ns 7 Crystal oscillator C1 OSC1 and OSC2: shown in Figure 2. 13 pF 8 C2 PF 8 C2 L 1.5 μH 8	Write command hold time	10 M		65			ns	7
Output data hold time t _{DHO} 100 ns 7 Crystal oscillator C1 OSC1 and OSC2: shown in Figure 2. 13 pF 8 C2 29 pF 8 Current design L 1.5 μH 8	Output data setup time	F S 4		30			ns	7
Crystal oscillator C1 OSC1 and OSC2: shown in Figure 2. 13 pF 8 C2 29 pF 8 C2 L 1.5 μH 8	Output data hold time	t _{DHO}		100			ns	7
C2	Cristal accillator	197.92	OSCA and OSCA about in Figure 2		13		pF	8
	Crystal oscillator	C2	rooc i and Gocz: snown in Figure 2.		29		pF	8
VDD1, VDD2, VDD3, OSCIIIAIOF Frequency: 33.8688 MHZ 60 95 mA 9	Current drain	L	1 1 V 2 V 2 coeillater fraguencii 22 0000 MII-		1.5		μH	8
V W YY91 1 1 12 2	Current drain	l _{DD}	F v _{DD} 1, v _{DB} ∠, v _{DD} 3; oscillator frequency: 33.8688 MHz		60	95	mA	9

Electrical Characteristics 2 at Ta = 25 $^{\circ}$ C, all V_{DD} = 5.0 V, all V_{SS} = 0 V unless otherwise specified

Parameter	Symbol	Conditions		min	typ	max	Unit	Note
[A/D Converter Block]	•				A sec			
		1 kHz, 0 dB: Lch			0.065	A. Section	%	10, 11
Total harmonic distortion	A-THD	1 kHz, 0 dB: Rch			√ 0 ₇ 065	Note of the State	%	10, 11
		1 kHz, 0 dB: Mic		J.	0.070	West of the second	%	10, 11
Signal-to-noise ratio	A-S/N	1 kHz, 0 dB		70	75	100	dB.	10, 11
Crosstalk	A-C · T	1 kHz, 0 dB		11	-72	Mary.	ď₿	10
[D/A Converter Block]	•			A A	130 r	100	And sealth	
Total harmonic distortion	D-THD	1 kHz, -1 dB	, and the second	g stor	0.045		/ .%	10
Signal-to-noise ratio	D-S/N	1 kHz, -1 dB	11		78		₫ dB	10
Crosstalk	D-C · T	1 kHz, –1 dB	A A	- CS	-75	A F	dB	10

- Note: 1. TTL output level pins: ASO, FS384O, BCKO, LRCKO, D0 to D7, A0 to A8, RAS, CAS, DREAD, DWRT
 - 2. CMOS intermediate current output pins: P3, P4, SIAK, TEST6
 - 3. N-channel open-drain intermediate current output pins: P0 to P2
 - 4. Low Schmitt input pins: BCKI, ASI, LRCKI, D0 to D7, FS384I
 - 5. Normal input pins: P0 to P2, TEST1 to TEST5, SELC, SAIF, SAOF
 - 6. Schmitt input pins: RES, SI, SICK, SIRQ, SRDY, OSC1
 - 7. When the load capacitance is 50 pF

 - The values for the oscillator capacitors C1 and C2 include the wiring capacitances.
 The value for the current drain is a typical value for V_{DD} = 5 V, room temperature, and a typical sample.
 - 10. With weight A filter present, with Fs = 44.1 kHz, and tested in the Sanyo evaluation board.
 - 11. Varies with the values of the external components. The listed value is for the circuit structure and values shown in Figure 9 in the Sanyo evaluation board.

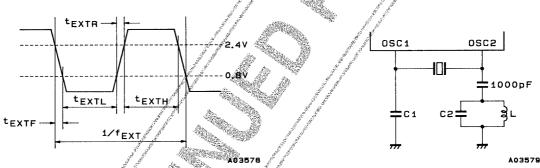


Figure 1 External Clock Input Waveform (FS384I)

Figure 2 Crystal Oscillator Circuit

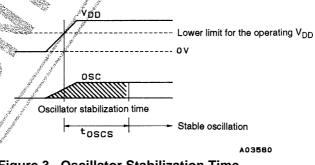


Figure 3 Oscillator Stabilization Time

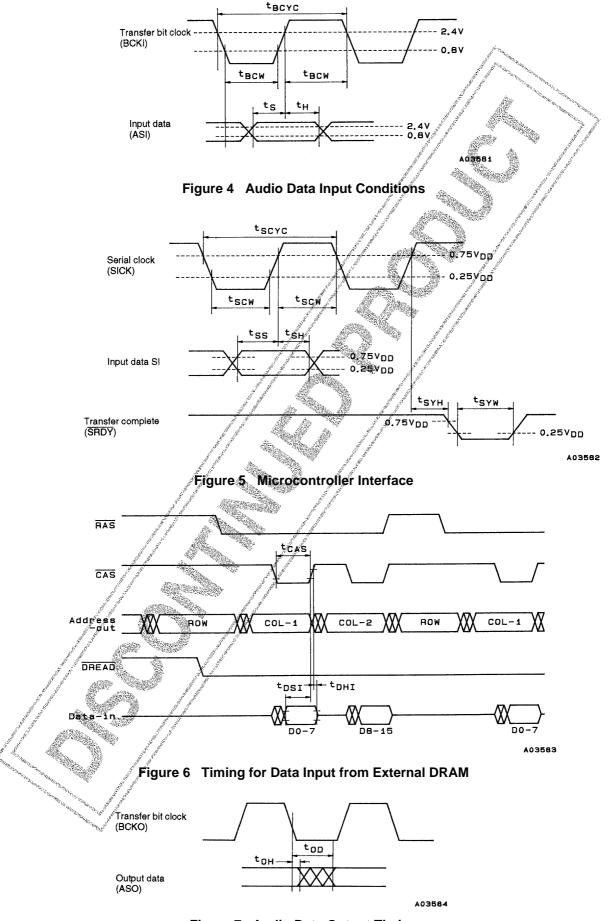


Figure 7 Audio Data Output Timing

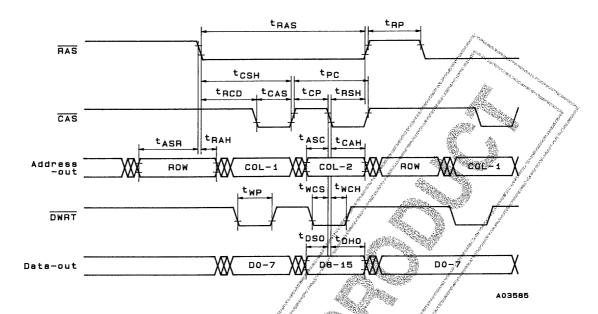


Figure 8 Timing for Data Output to External DRAM

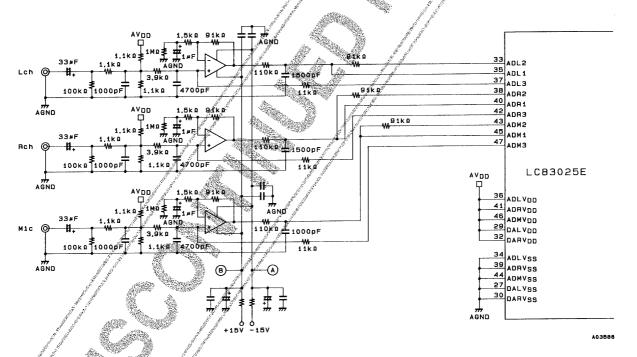
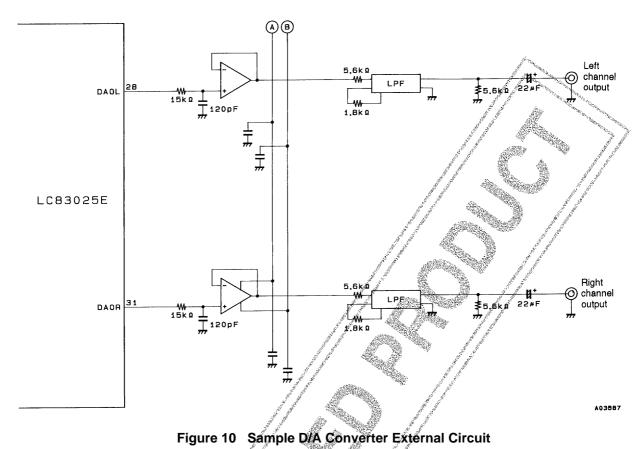
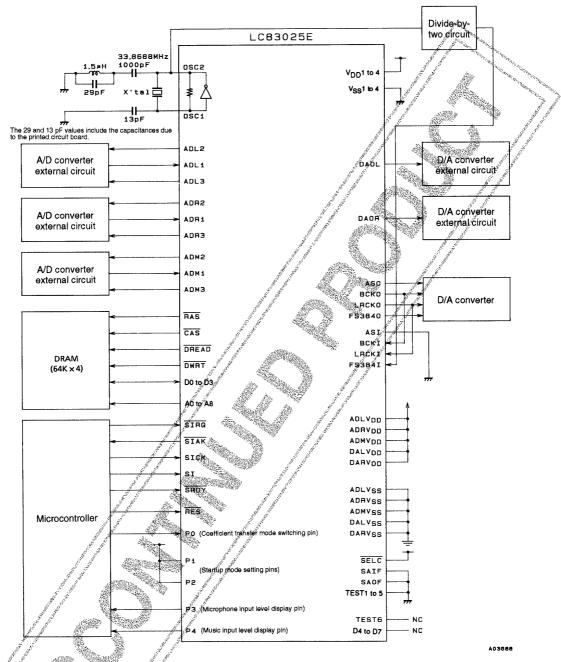


Figure 9 Sample A/D Converter External Circuit

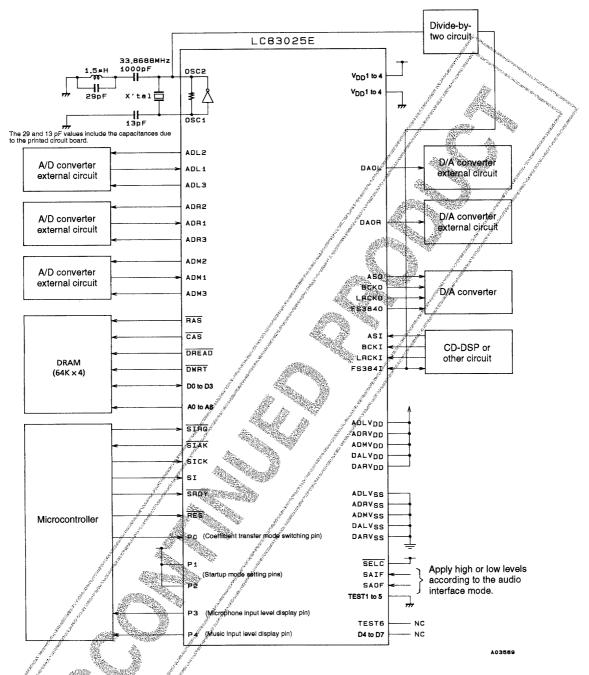


Sample Peripheral Circuit Connection (For applications that do not use digital input)

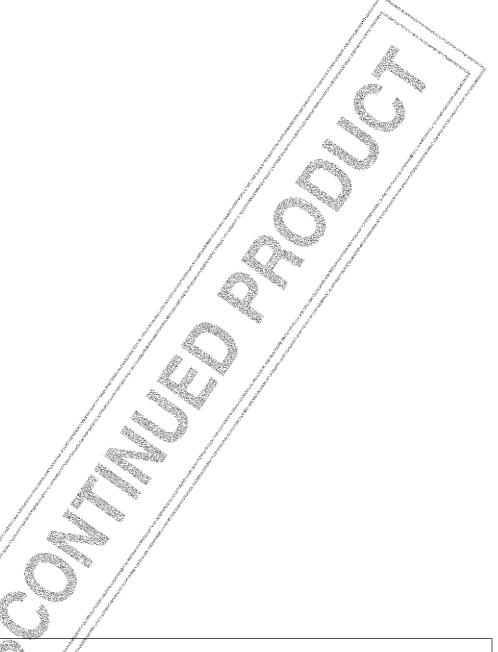


Whether or not the digital outputs and the analog L/R outputs will be used will be determined by the end product specifications. These pins should be left open if unused.

Sample Peripheral Circuit Connection (For applications that use digital input.)



Whether or not the analog L/R inputs and the analog L/R outputs will be used will be determined by the end product specifications. A high or low level should be applied to unused input pins, and unused output pins should be left open.



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